

Amendments to the Abstract:

An electrode on a main surface of a module board, to which an emitter electrode of a semiconductor chip ~~formed with~~ which includes a switching element of a power supply control circuit that supplies a power supply voltage to amplifier circuit parts of a power module of a digital cellular phone, is electrically connected to a wiring in an internal layer of the module board through a plurality of via ~~holes~~ viaholes. Further, the wiring ~~CL1~~ is electrically connected to an electrode for the supply of the power supply voltage, which is provided on a back surface of the module board. Accordingly, an output characteristic of the semiconductor device is improved.